2SA2004

Silicon PNP epitaxial planar type

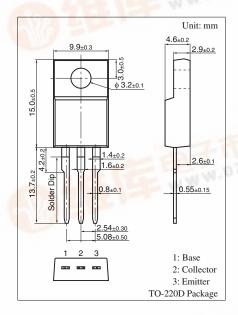
For power amplification

■ Features

- High forward current transfer ratio h_{FE}
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Dielectric breakdown voltage of the package: > 5 kV
- High-speed switching

■ Absolute Maximum Ratings $T_C = 25^{\circ}C$

| Parameter | | Symbol | Rating | Unit |
|------------------------------|---------------------|------------------|-------------|------|
| Collector to base voltage | | V_{CBO} | -60 | V |
| Collector to emitter voltage | | V_{CEO} | -60 | V |
| Emitter to base voltage | | V _{EBO} | -5 | V |
| Peak collector current | | I_{CP} | -16 | A |
| Collector current | | I_C | -8 | A |
| Collector power | $T_C = 25^{\circ}C$ | P_{C} | 20 | W |
| dissipation | $T_a = 25^{\circ}C$ | | 2.0 | |
| Junction temperature | | T_j | 150 | °C |
| Storage temperature | | T_{stg} | -55 to +150 | °C |



■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---|----------------------|--|-----|-------|------|------|
| Collector cutoff current | I_{CBO} | $V_{CB} = -60 \text{ V}, I_E = 0$ | | | -100 | μА |
| 2000 | I_{CEO} | $V_{CE} = -60 \text{ V}, I_{E} = 0$ | | | -100 | μA |
| Collector to emitter voltage | V_{CEO} | $I_{\rm C} = -10 \text{ mA}, I_{\rm B} = 0$ | -60 | | | V |
| Forward current transfer ratio | h _{FE1} | $V_{CE} = -2 \text{ V}, I_C = -0.1 \text{ A}$ | 100 | | 230 | 177 |
| | h _{FE2} | $V_{CE} = -2 \text{ V}, I_{C} = -5 \text{ A}$ | 30 | N. F. | - 4 | MAL |
| Collector to emitter saturation voltage | V _{CE(sat)} | $I_C = -5 \text{ A}, I_B = -0.25 \text{ A}$ | | | -1.2 | V |
| Base to emitter saturation voltage | V _{BE(sat)} | $I_C = -5 \text{ A}, I_C = -0.25 \text{ A}$ | | | -1.7 | V |
| Turn-on time | t _{on} | $I_C = -4 \text{ A}, I_{B1} = -400 \text{ mA}$ | | 0.2 | 0.5 | μs |
| Storage time | t _{stg} | $I_{B2} = 400 \text{ mA}, V_{CC} = 50 \text{ V}$ | | 0.1 | 0.15 | μs |
| Fall time | $t_{\rm f}$ | | | 0.5 | 1.0 | μs |



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